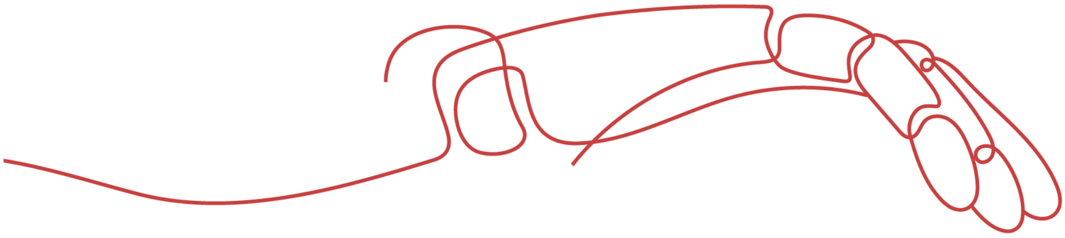
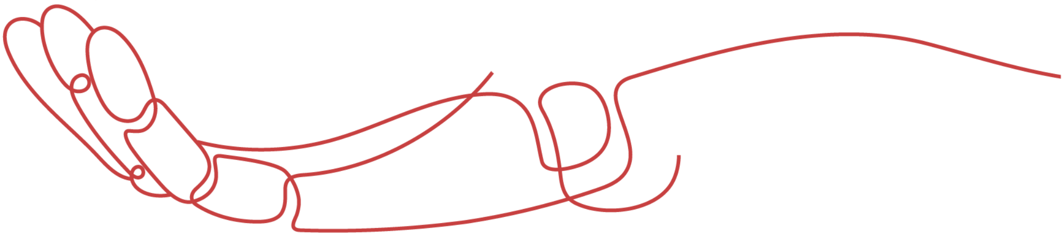
JG Techology



PRODUCT DATA SHEET



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Datasheet **Resources** **Samples**

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
30V	7.9mΩ	45A

Features

- *30V,45A, RDS(ON) =7.9mΩ@VGS = 10V*
- *Improved dv/dt capability*
- *Fast switching*
- *100% EAS Guaranteed*
- *Green Device Available*

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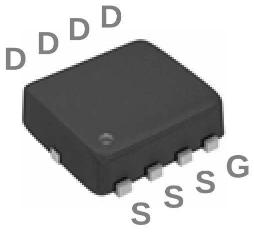

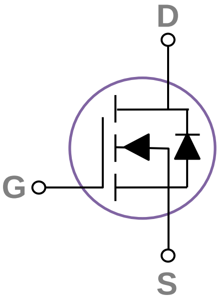

Applications

- *Networking*
- *Load Switch*
- *LED applications*

Absolute Maximum Ratings Tc=25℃ unless otherwise noted

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Drain Current – Continuous (T_C=25℃)	45	A
	Drain Current – Continuous (T_C=100℃)	28.5	A
I_{DM}	Drain Current – Pulsed[1]	180	A
EAS	Single Pulse Avalanche Energy[2]	45	mJ
IAS	Single Pulse Avalanche Current[2]	30	A
P_D	Power Dissipation (T_C=25℃)	30	W
	Power Dissipation – Derate above 25℃	0.24	W/℃
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	4.15	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	30	---	---	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=30V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J=125℃	---	---	10	uA
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=10V , I_D=15A	---	6.6	7.9	mΩ
		V_{GS}=4.5V , I_D=10A	---	9.2	12	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.2	1.6	2.5	V
gfs	Forward Transconductance	V_{DS}=10V , I_D=3A	---	20	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge[3,4]	V_{DS}=15V , V_{GS}=10V , I_D=25A	---	15	23	nC
Q_{gs}	Gate-Source Charge[3,4]		---	1.8	3	
Q_{gd}	Gate-Drain Charge[3,4]		---	4	6	
$T_{d(on)}$	Turn-On Delay Time[3,4]	V_{DD}=15V , V_{GS}=10V , R_G=6Ω I_D=25A	---	5	7.5	ns
T_r	Rise Time[3,4]		---	13	20	
$T_{d(off)}$	Turn-Off Delay Time[3,4]		---	28	42	
T_f	Fall Time[3,4]		---	8	12	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , F=1MHz	---	900	1350	pF
C_{oss}	Output Capacitance		---	130	200	
C_{rss}	Reverse Transfer Capacitance		---	110	170	
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz	---	2	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	V_G=V_D=0V , Force Current	---	---	45	A
I_{SM}	Pulsed Source Current		---	---	90	A
V_{SD}	Diode Forward Voltage	V_{GS}=0V , I_S=1A , T_J=25℃	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=30A.,R_G=25Ω,Starting T_J=25℃.
3. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
4. Essentially independent of operating temperature.

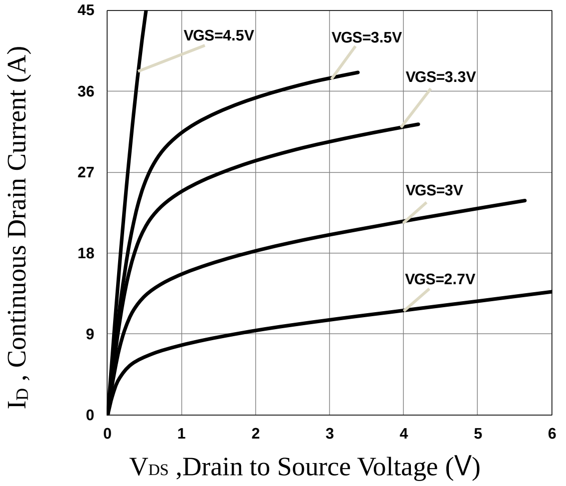

Fig.1 Typical Output Characteristics

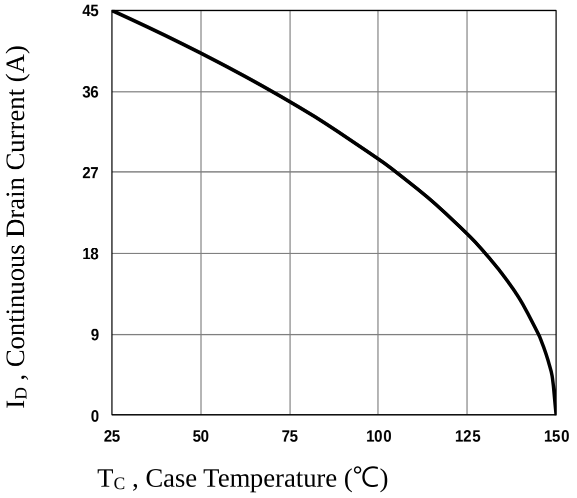

Fig.2 Continuous Drain Current vs. T_C

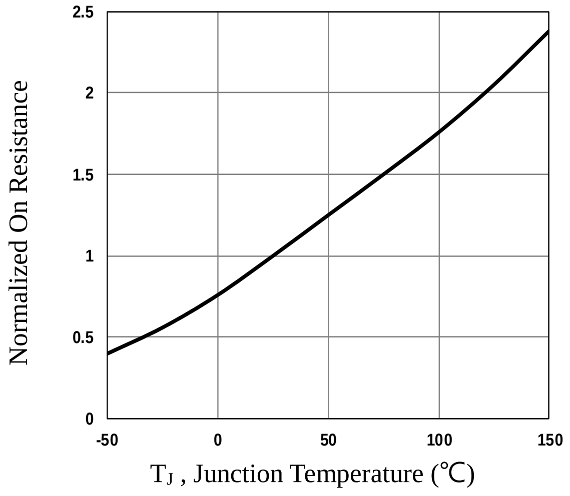

Fig.3 Normalized RDSON vs. T_J

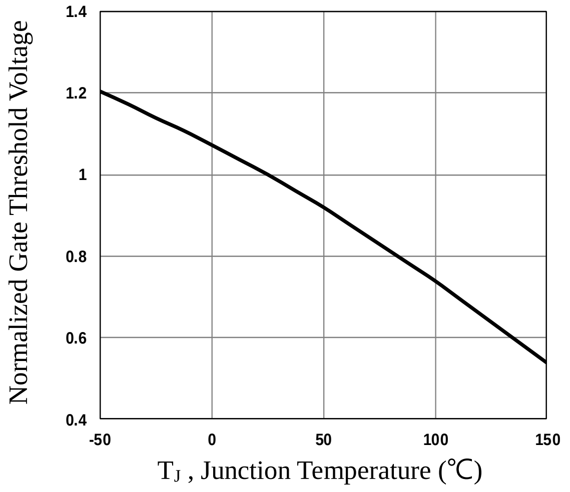

Fig.4 Normalized V_{th} vs. T_J

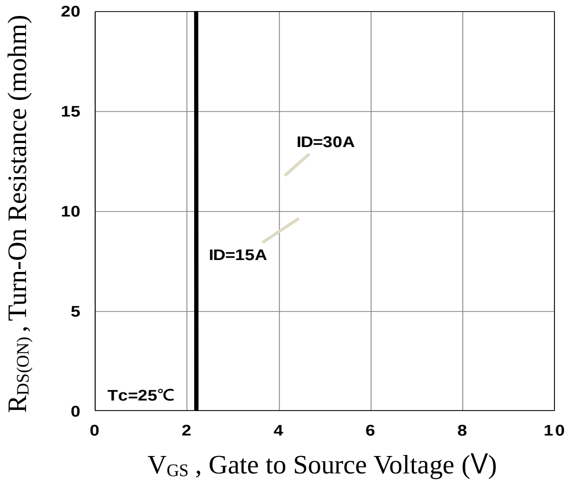

Fig.5 Turn-On Resistance vs. V_{GS}

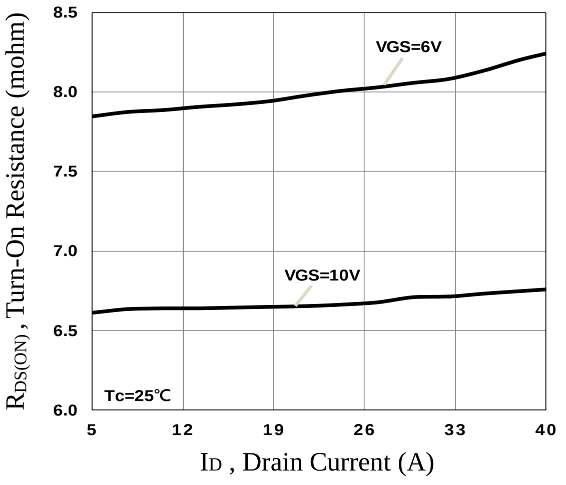

Fig.6 Turn-On Resistance vs. I_D

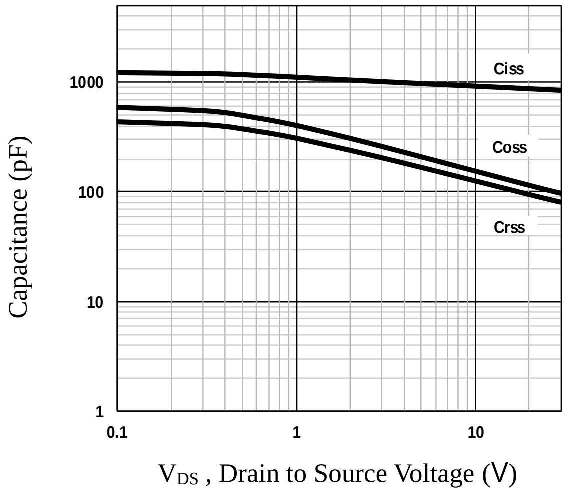

Fig.7 Capacitance Characteristics

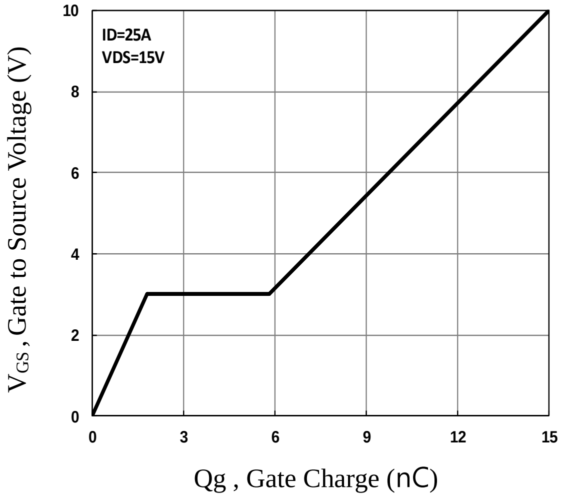

Fig.8 Gate Charge Characteristics

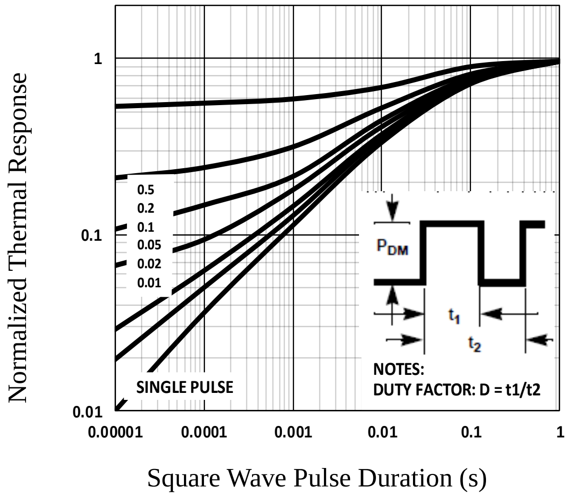

Fig.9 Normalized Transient Impedance

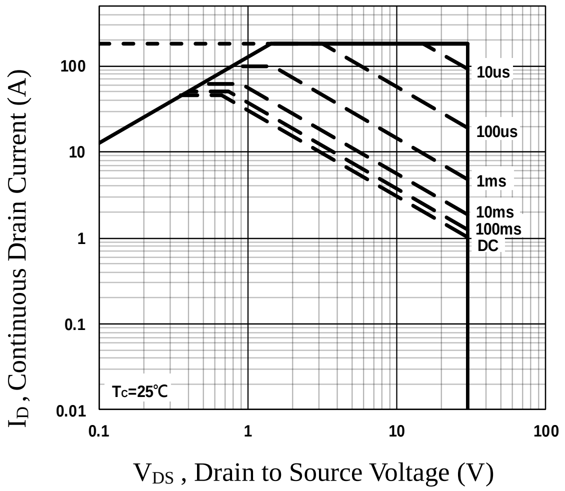

Fig.10 Maximum Safe Operation Area

$$EAS=\frac{1}{2}L \times I_{AS}^{2} \times \frac{BV_{DSS}}{BV_{DSS}-V_{DD}}$$

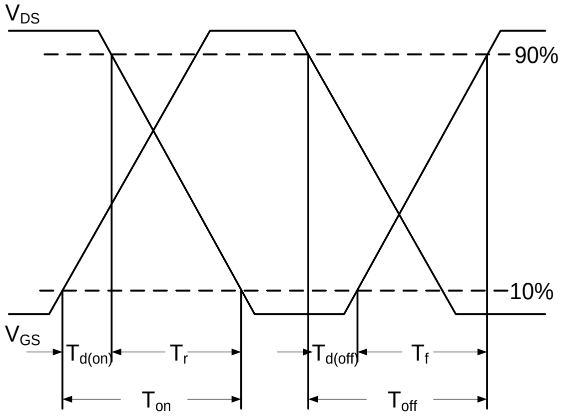

Fig.11 Switching Time Waveform

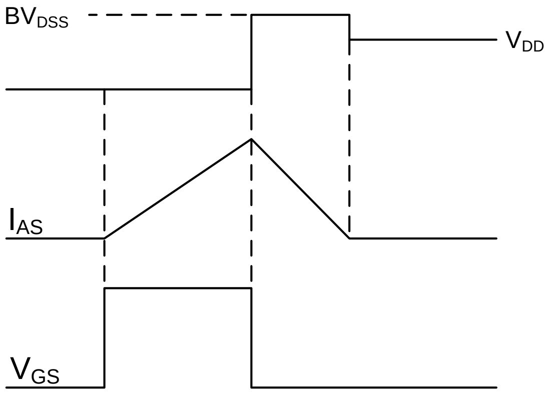

Fig.12 EAS Waveform

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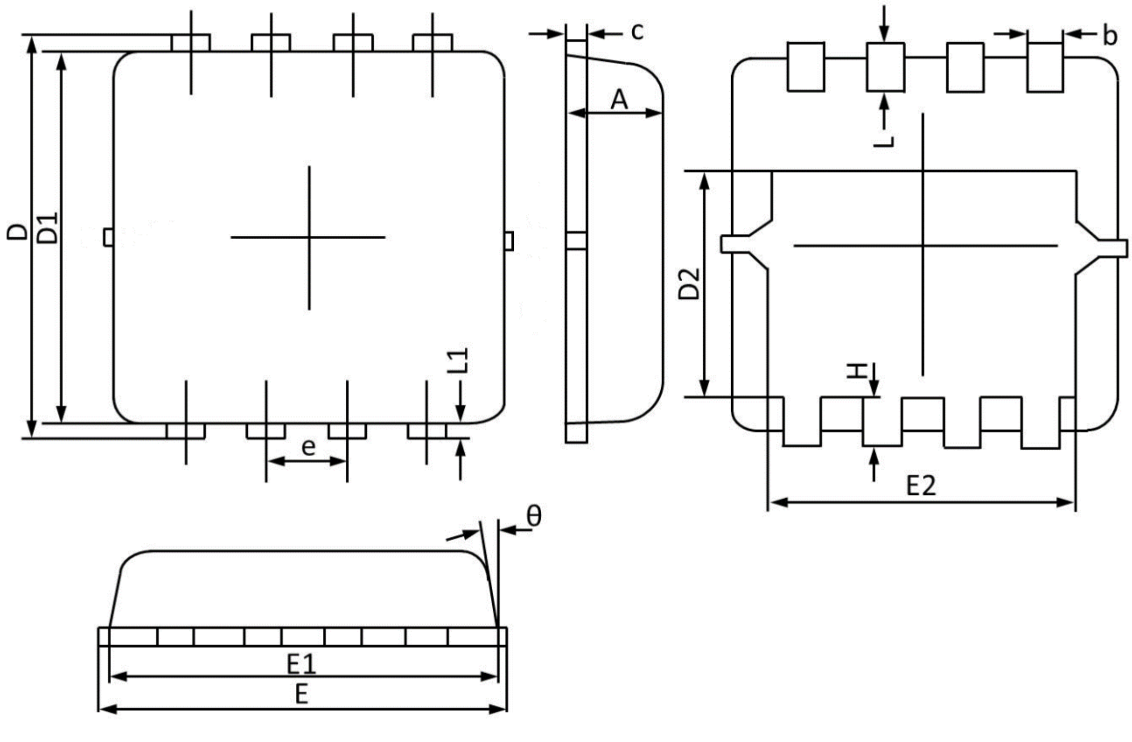

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.250	0.014	0.010
c	0.250	0.100	0.010	0.004
D	3.500	3.050	0.138	0.120
D1	3.200	2.900	0.126	0.114
D2	1.950	1.350	0.077	0.053
E	3.400	3.000	0.134	0.118
E1	3.300	2.900	0.130	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.750	0.300	0.030	0.012
L	0.600	0.300	0.024	0.012
L1	0.200	0.060	0.008	0.002
θ	14°	6°	14°	6°

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